

#2/A
Pb
4/30/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Kazuhiro OTSU et al.

Serial No. [NEW] : Attn: Application Branch

Filed February 7, 2002 : Attorney Docket No. 2002-0208A

SEPARATING MACHINE FOR THINNED
SEMICONDUCTOR SUBSTRATE AND
SEPARATION METHOD

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEE FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975.

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

In the interest of compact prosecution and to reduce PTO filing fees, please amend the present application as follows:

IN THE CLAIMS:

Please rewrite claim 4 as follows:

A1
4. (Amended) A separating machine for a thinned semiconductor substrate according to claim 2, wherein the system for making a starting point for the separation is a system of pressing with a knife edge.

Please add the following new claim:

A2
9. (New) A separating machine for a thinned semiconductor substrate according to claim 3, wherein the system for making a starting point for the separation is a system of pressing with a knife edge.